

5.0X6.0mm SURFACE MOUNT LED LAMP

AA5060SEC/E

HYPER ORANGE

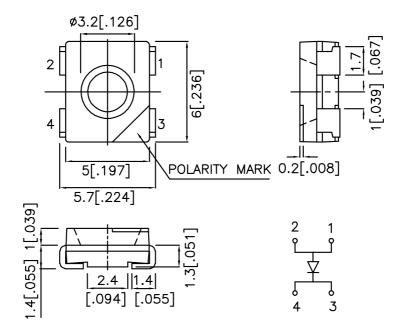
Features

- SINGLE COLOR.
- SUITABLE FOR ALL SMT ASSEMBLY AND SOLDER PROCESS.
- AVAILABLE ON TAPE AND REEL.
- IDEAL FOR BACKLIGHTING.
- PACKAGE: 500PCS / REEL.
- RoHS COMPLIANT.

Description

The Hyper Orange source color devices are made with DH InGaAIP on GaAs substrate Light Emitting Diode.

Package Dimensions



Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.
- 3. Specifications are subject to change without notice.

SPEC NO: DSAD0899 APPROVED: J. Lu REV NO: V.6 CHECKED: Allen Liu DATE: MAR/14/2005 DRAWN: B.H.LI PAGE: 1 OF 4 ERP: 1201000530

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Selection Guide

Part No.	Dice	Lens Type	lv (mcd) @ 50mA		Viewing Angle
			Min.	Тур.	201/2
AA5060SEC/E	HYPER ORANGE(InGaAIP)	WATER CLEAR	650	1000	100°

Note

Electrical / Optical Characteristics at T_A=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Hyper Orange	630		nm	IF=20mA
λD	Dominant Wavelength	Hyper Orange	621		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Hyper Orange	20		nm	IF=20mA
С	Capacitance	Hyper Orange	25		pF	VF=0V;f=1MHz
VF	Forward Voltage	Hyper Orange	2.0	2.5	V	IF=20mA
lR	Reverse Current	Hyper Orange		10	uA	VR = 5V

Absolute Maximum Ratings at TA=25°C

Parameter	Hyper Orange	Units
Power dissipation	125	mW
DC Forward Current	50	mA
Peak Forward Current [1]	195	mA
Reverse Voltage	5	V
Operating/Storage Temperature	-40°C To +85°C	

Note

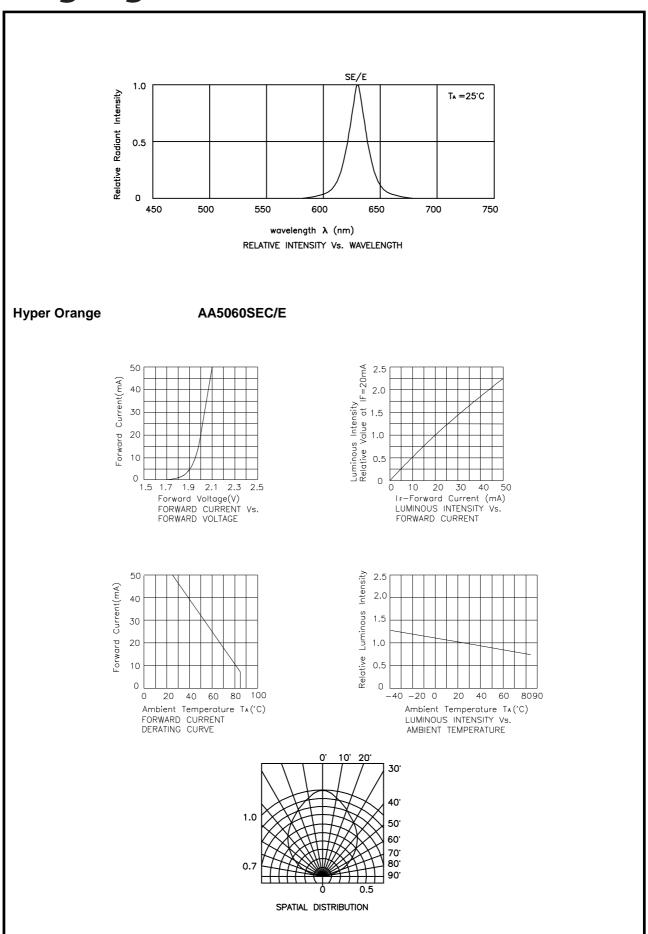
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 $^{1.\,\}theta 1/2 \text{ is the angle from optical centerline where the luminous intensity is } 1/2 \text{ the optical centerline value}.$

^{1. 1/10} Duty Cycle, 0.1ms Pulse Width.

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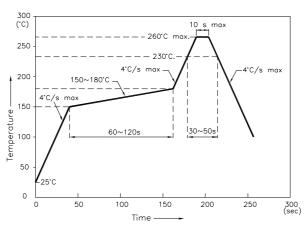
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Reflow Soldering Profile For Lead-free SMT Process.

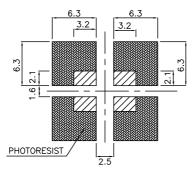


- NOTES:

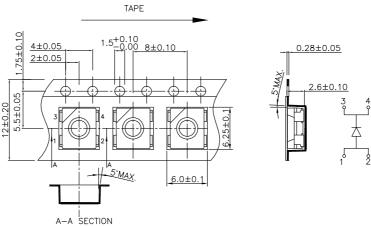
 1. We recommend the reflow temperature $245^{\circ}\text{C}(+/-5^{\circ}\text{C})$. The maximum soldering temperature should be limited to 260°C.
 - 2.Don't cause stress to the epoxy resin while it is exposed to high temperature.
 - 3. Number of reflow process shall be 2 times or less.

Recommended Soldering Pattern

(Units: mm)



Tape Specifications (Units: mm)



If special sorting is required (e.g. binning based on forward voltage, luminous intensity, or wavelength), the typical accuracy of the sorting process is as follows:

- 1. Wavelength: +/-1nm
- 2. Luminous Intensity: +/-15%
- 3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

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